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**RESIN-SEALED SEMICONDUCTOR DEVICE AND LEAD FRAME USED FOR IT,
AND MANUFACTURE OF RESIN-SEALED SEMICONDUCTOR DEVICE**

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Abstract:

PURPOSE: To raise occupancy rate of a chip and to miniaturize a semiconductor device by fixing a plurality of lead parts wherein an inside terminal part and an outside terminal part are integrated to a semiconductor element surface through an insulation adhesive layer and by connecting an outside electrode part consisting of solder to an outside terminal part.

CONSTITUTION: A plurality of lead parts 102 wherein an inside terminal part 102A, an outside terminal part 102B and a connection lead part 102C are integrated are sealed and provided to a terminal side surface of a semiconductor element 101 through an insulation adhesive layer 104. An outside electrode 106 consisting of solder for mounting on a circuit substrate, etc., is connected to an outside terminal part 102B of each of a plurality of leads 102. At least a part of the outside electrode 106 consisting of solder is provided to be exposed to an outside from a resin part 105. Thereby, it is possible to raise occupation rate of a chip in a package size of a semiconductor device to correspond to miniaturization of a semiconductor device and to reduce the mounting area of the semiconductor device on a circuit substrate.

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